



# STGW30NC120HD

N-CHANNEL 30A - 1200V - TO-247  
VERY FAST PowerMESH™ IGBT

TARGET SPECIFICATION

## General features

Type	$V_{CES}$	$V_{CE(sat)}$ (Max) @ 25°C	$I_C$
STGW30NC120HD	1200V	< 2.8V	30A

- LOW ON-LOSSES
- LOW ON-VOLTAGE DROP ( $V_{cesat}$ )
- HIGH CURRENT CAPABILITY
- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)
- LOW GATE CHARGE
- VERY HIGH FREQUENCY OPERATION
- LATCH CURRENT FREE OPERATION

## Description

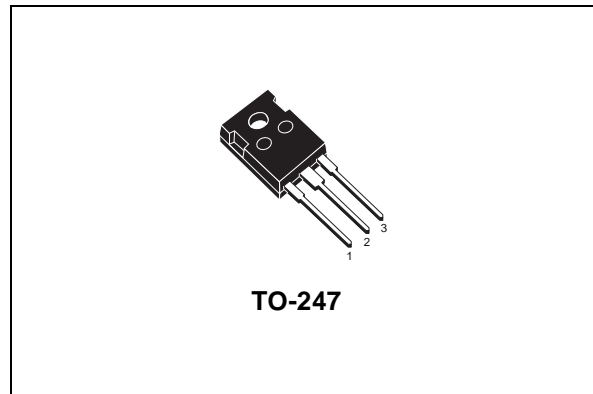
Using the latest high voltage technology based on its patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, with outstanding performances. The suffix "H" identifies a family optimized for high frequency application in order to achieve very high switching performances (reduced  $t_{fall}$ ) maintaining a low voltage drop.

## Applications

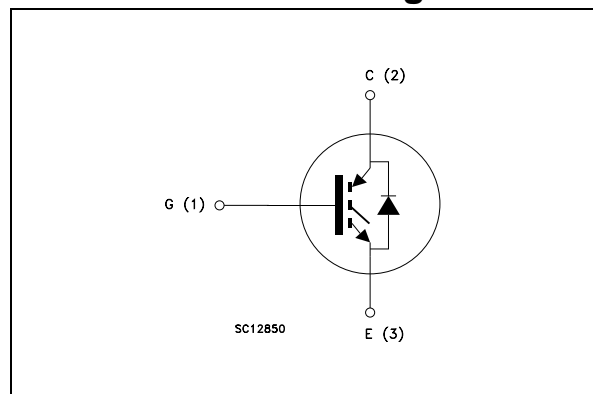
- HIGH FREQUENCY MOTOR CONTROL
- U.P.S
- WELDING EQUIPMENT
- INDUCTION HEATING

## Order codes

Sales Type	Marking	Package	Packaging
STGW30NC120HD	GW30NC120HD	TO-247	TUBE



## Internal schematic diagram



# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-Emitter Voltage ( $V_{GS} = 0$ )	1200	V
$I_C$ <i>Note 2</i>	Collector Current (continuous) at 25°C	60	A
$I_C$ <i>Note 2</i>	Collector Current (continuous) at 100°C	30	A
$I_{CM}$ <i>Note 1</i>	Collector Current (pulsed)	120	A
$V_{GE}$	Gate-Emitter Voltage	$\pm 20$	V
$P_{TOT}$	Total Dissipation at $T_C=25^\circ\text{C}$	200	W
$I_f$	Diode RMS Forward Current at $T_C=25^\circ\text{C}$	200	
$T_j$	Operating Junction Temperature	– 55 to 150	°C
$T_{stg}$	Storage Temperature		

**Table 2. Thermal resistance**

		Min.	Typ.	Max.	Unit
Rthj-case	Thermal Resistance Junction-case	--	--	0.625	°C/W
Rthj-amb	Thermal Resistance Junction-ambient	--	--	50	°C/W

## 2 Electrical characteristics

( $T_{CASE} = 25\text{ °C}$  unless otherwise specified)

**Table 3. Static**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{BR(CES)}$	Collectro-Emitter Breakdown Voltage	$I_C = 250\mu A, V_{GE} = 0$	1200			V
$V_{CE(SAT)}$	Collector-Emitter Saturation Voltage	$V_{GE} = 15V, I_C = 20A, T_j = 25\text{ °C}$ $V_{GE} = 15V, I_C = 20A, T_j = 125\text{ °C}$		2.4 2	2.9	V V
$V_{GE(th)}$	Gate Threshold Voltage	$V_{CE} = V_{GE}, I_C = 250\mu A$	5		7	V
$I_{CES}$	Collector-Emitter Leakage Current ( $V_{CE} = 0$ )	$V_{GE} = \text{Max Rating}, T_c = 25\text{ °C}$ $V_{GE} = \text{Max Rating}, T_c = 125\text{ °C}$			10 100	$\mu A$ $\mu A$
$I_{GES}$	Gate-Emitter Leakage Current ( $V_{CE} = 0$ )	$V_{GE} = \pm 20V, V_{CE} = 0$			$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{CE} = 25V, I_C = 25A$		TBD		S

**Table 4. Dynamic**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input Capacitance	$V_{CE} = 25V, f = 1\text{ MHz}, V_{GE} = 0$		TBD		pF
$C_{oes}$	Output Capacitance			TBD		pF
$C_{res}$	Reverse Transfer Capacitance			TBD		pF
Qg	Total Gate Charge	$V_{CE} = 960V, I_C = 20A, V_{GE} = 15V$		TBD	TBD	nC
Qge	Gate-Emitter Charge			TBD		nC
Qgc	Gate-Collector Charge			TBD		nC

**Table 5. Switching on/off (inductive load)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ $t_r$ $(di/dt)_{on}$	Turn-on Delay Time Current Rise Time Turn-on Current Slope	$V_{CC} = 960V, I_C = 20A$ $R_G = 10\Omega, V_{GE} = 15V, T_j = 25^\circ C$ (see Figure 3)		TBD 62 TBD		ns ns A/ $\mu s$
$t_{d(on)}$ $t_r$ $(di/dt)_{on}$	Turn-on Delay Time Current Rise Time Turn-on Current Slope	$V_{CC} = 960V, I_C = 20A$ $R_G = 10\Omega, V_{GE} = 15V, T_j = 125^\circ C$ (see Figure 3)		TBD TBD TBD		ns ns A/ $\mu s$
$t_r(V_{off})$ $t_{d(off)}$ $t_f$	Off Voltage Rise Time Turn-off Delay Time Current Fall Time	$V_{CC} = 960V, I_C = 20A$ $R_G = 10\Omega, V_{GE} = 15V, T_j = 25^\circ C$ (see Figure 3)		TBD TBD TBD		ns ns ns
$t_r(V_{off})$ $t_{d(off)}$ $t_f$	Cross-over Time Off Voltage Rise Time Turn-off Delay Time Current Fall Time	$V_{CC} = 960V, I_C = 20A$ $R_G = 10\Omega, V_{GE} = 15V, T_j = 125^\circ C$ (see Figure 3)		TBD TBD TBD		ns ns ns

**Table 6. Switching energy (inductive load)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$E_{on}$ <i>Note 3</i> $E_{off}$ <i>Note 4</i> $E_{ts}$	Turn-on Switching Losses Turn-off Switching Losses Total Switching Losses	$V_{CC} = 960V, I_C = 20A$ $R_G = 10\Omega, V_{GE} = 15V, T_j = 25^\circ C$ (see Figure 3)		TBD TBD TBD		$\mu J$ $\mu J$ $\mu J$
$E_{on}$ <i>Note 3</i> $E_{off}$ <i>Note 4</i> $E_{ts}$	Turn-on Switching Losses Turn-off Switching Losses Total Switching Losses	$V_{CC} = 960V, I_C = 20A$ $R_G = 10\Omega, V_{GE} = 15V, T_j = 125^\circ C$ (see Figure 3)		TBD TBD TBD		$\mu J$ $\mu J$ $\mu J$

**Table 7. Collector-emitter diode**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_f$	Forward On-Voltage	$I_f = 12A$ $I_f = 12A, T_j = 125^\circ C$		2.4 1.4	2.9	V V
$t_{rr}$ $Q_{rr}$ $I_{rrm}$	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_f = 12A, V_R = 27V,$ $T_j = 125^\circ C, di/dt = 100A/\mu s$ (see Figure 4)		TBD TBD TBD		ns nC A

(1) Pulse width limited by max junction temperature

(2) Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{JMAX} - T_C}{R_{THJ-C} \times V_{CESAT(MAX)}(T_C, I_C)}$$

(3)  $E_{on}$  is the turn-on losses when a typical diode is used in the test circuit in figure 2. If the IGBT is offered in a package with a co-pack diode, the co-pack diode is used as external diode. IGBTs & Diode are at the same temperature (25°C and 125°C)

(4) Turn-off losses include also the tail of the collector current

### 3 Test Circuits

Figure 1. Test Circuit for Inductive Load Switching

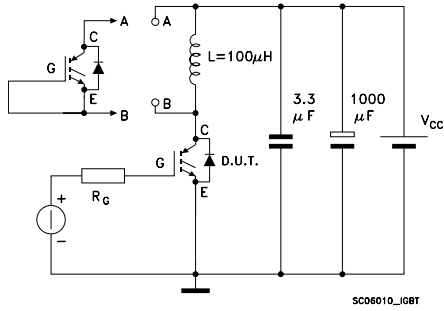


Figure 2. Gate Charge Test Circuit

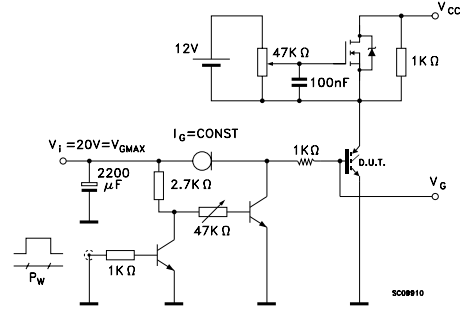


Figure 3. Switching Waveform

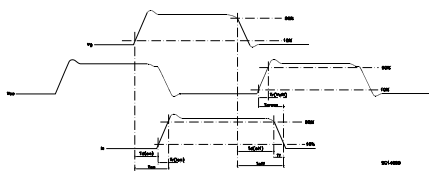
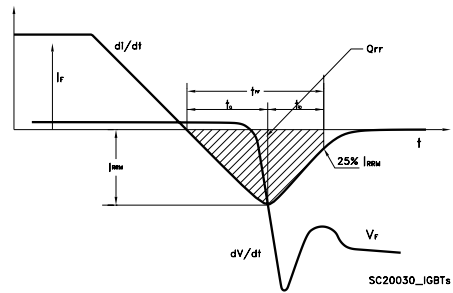


Figure 4. Diode Recovery Time Waveform

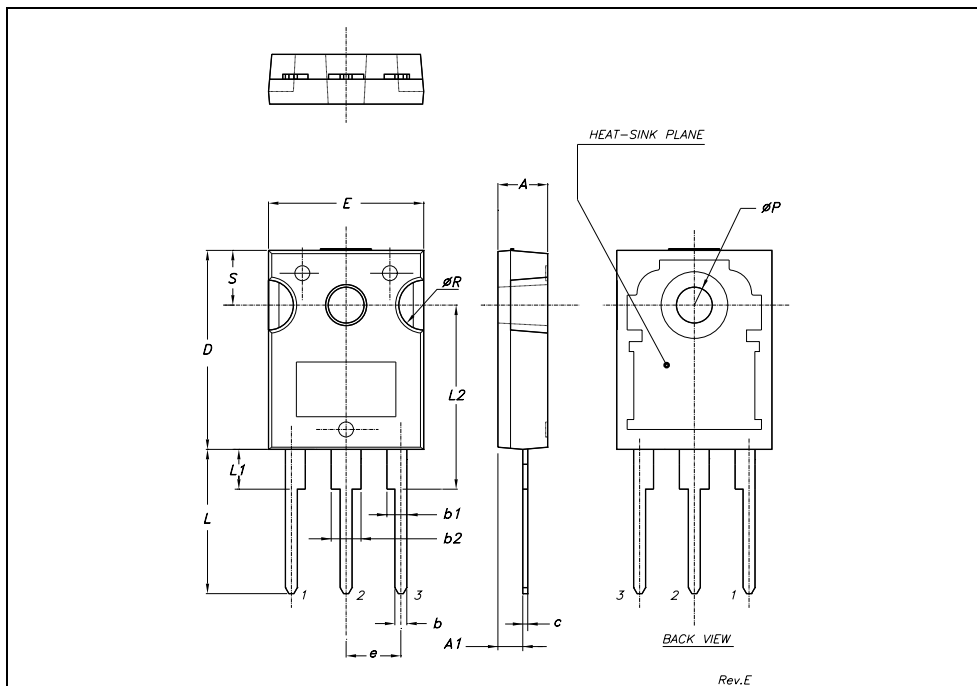


## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

**TO-247 MECHANICAL DATA**

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.85		5.15	0.19		0.20
A1	2.20		2.60	0.086		0.102
b	1.0		1.40	0.039		0.055
b1	2.0		2.40	0.079		0.094
b2	3.0		3.40	0.118		0.134
c	0.40		0.80	0.015		0.03
D	19.85		20.15	0.781		0.793
E	15.45		15.75	0.608		0.620
e		5.45			0.214	
L	14.20		14.80	0.560		0.582
L1	3.70		4.30	0.14		0.17
L2		18.50			0.728	
øP	3.55		3.65	0.140		0.143
øR	4.50		5.50	0.177		0.216
S		5.50			0.216	



## 5 Revision History

Date	Revision	Changes
14-Nov-2005	1	Initial release.



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